

# **High Current Transistors NPN** Silicon

# BC489, A, B

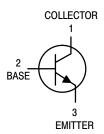
#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	VCEO	80	Vdc
Collector–Base Voltage	VCBO	80	Vdc
Emitter-Base Voltage	VEBO	5.0	Vdc
Collector Current — Continuous	IC	0.5	Adc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	PD	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	PD	1.5 12	Watt mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C



#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction to Case	$R_{ heta}$ JC	83.3	°C/W



### **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

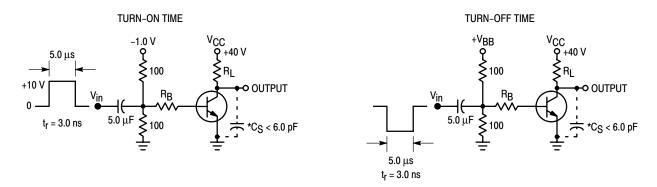
	<u> </u>					
Characteristi	С	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Collector–Emitter Breakdown Voltage(1) (I <sub>C</sub> = 10 mAdc, I <sub>B</sub> = 0)		V(BR)CEO	80	_	_	Vdc
Collector–Base Breakdown Voltage (IC = 100 µAdc, IE = 0)		V(BR)CBO	80	_	_	Vdc
Emitter–Base Breakdown Voltage (I <sub>E</sub> = 10 μAdc, I <sub>C</sub> = 0)		V(BR)EBO	5.0	_	_	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 60 Vdc, I <sub>E</sub> = 0)		СВО	_	_	100	nAdc
ON CHARACTERISTICS*						
DC Current Gain (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 2.0 Vdc) (I <sub>C</sub> = 100 mAdc, V <sub>CE</sub> = 2.0 Vdc)	BC489 BC489A BC489B	hFE	40 60 100 160	  160 260	 400 250 400	_
$(I_C = 1.0 \text{ Adc}, V_{CE} = 5.0 \text{ Vdc})^*$			15	<u> </u>	<u> </u>	

<sup>1.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle 2%.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25$ °C unless otherwise noted) (Continued)

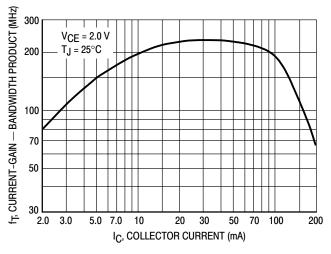
· //	· ,				
Characteristic	Symbol	Min	Тур	Max	Unit
ON CHARACTERISTICS* (Continued)					
Collector–Emitter Saturation Voltage (I <sub>C</sub> = 500 mAdc, I <sub>B</sub> = 50 mAdc) (I <sub>C</sub> = 1.0 Adc, I <sub>B</sub> = 100 mAdc)	VCE(sat)	_ _	0.2 0.3	0.5	Vdc
Base–Emitter Saturation Voltage ( $I_C = 500 \text{ mAdc}$ , $I_B = 50 \text{ mAdc}$ ) ( $I_C = 1.0 \text{ Adc}$ , $I_B = 100 \text{ mAdc}$ )(1)	V <sub>BE</sub> (sat)	_	0.85 0.9	1.2 —	Vdc
DYNAMIC CHARACTERISTICS					
Current–Gain — Bandwidth Product (I <sub>C</sub> = 50 mAdc, V <sub>CE</sub> = 2.0 Vdc, f = 100 MHz)	fT	_	200	_	MHz
Output Capacitance (V <sub>CB</sub> = 10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>ob</sub>	_	7.0	_	pF
Input Capacitance (VEB = 0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)	C <sub>ib</sub>	_	50	_	pF

<sup>1.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle 2.0%.



\*Total Shunt Capacitance of Test Jig and Connectors For PNP Test Circuits, Reverse All Voltage Polarities

Figure 1. Switching Time Test Circuits



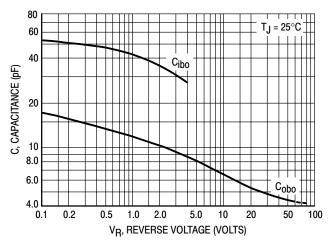


Figure 2. Current-Gain — Bandwidth Product

Figure 3. Capacitance

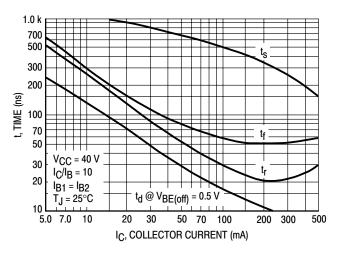


Figure 4. Switching Time

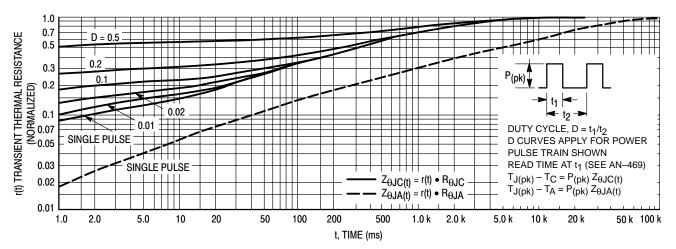


Figure 5. Thermal Response

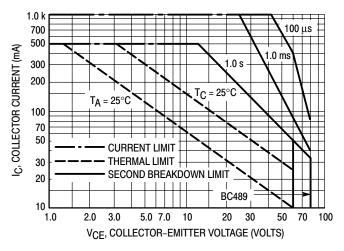


Figure 6. Active Region — Safe Operating Area

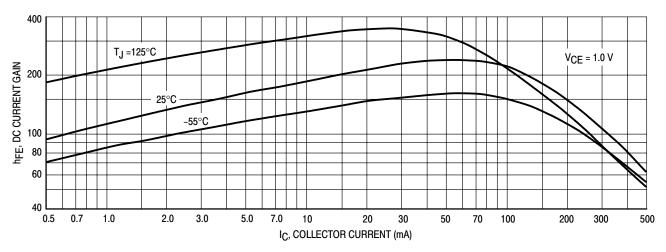


Figure 7. DC Current Gain

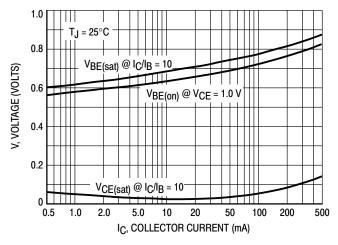


Figure 8. "On" Voltages

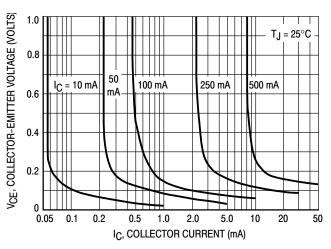


Figure 9. Collector Saturation Region

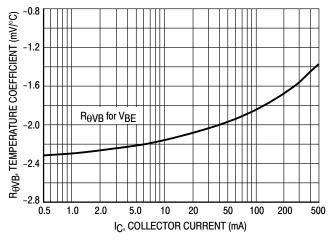


Figure 10. Base-Emitter Temperature Coefficient

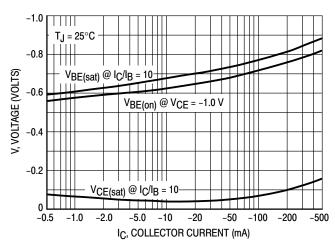


Figure 11. "On" Voltages

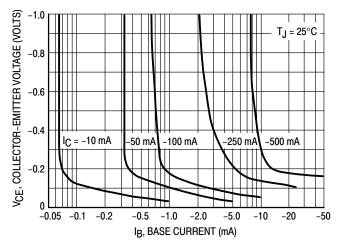


Figure 12. Collector Saturation Region

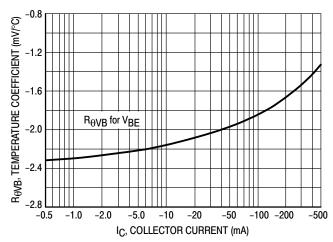
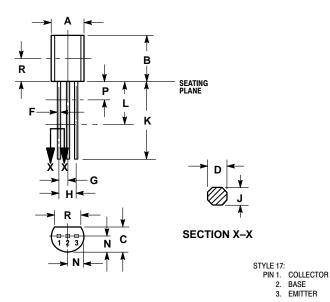


Figure 13. Base-Emitter Temperature Coefficient

### **PACKAGE DIMENSIONS**

## CASE 029-04 (TO-226AA) ISSUE AD



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
  4. DIMENSION F APPLIES BETWEEN P AND L. DIMENSIONS D AND J APPLY BETWEEN L AND K MIMIMUM. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

١		INC	HES	MILLIN	IETERS
l	DIM	MIN	MAX	MIN	MAX
	Α	0.175	0.205	4.44	5.21
	В	0.290	0.310	7.37	7.87
	С	0.125	0.165	3.18	4.19
	D	0.018	0.021	0.457	0.533
	F	0.016	0.019	0.407	0.482
	G	0.045	0.055	1.15	1.39
	Н	0.095	0.105	2.42	2.66
	J	0.018	0.024	0.46	0.61
	K	0.500		12.70	
	L	0.250		6.35	
	N	0.080	0.105	2.04	2.66
	Р		0.100		2.54
	R	0.135		3.43	

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